

LNPTM THERMOCOMPTM COMPOUND ZX08309

DESCRIPTION

This material is mineral filled PPO grade with high dielectric constant and low loss tangent

TYPICAL PROPERTY VALUES

Revision 20191213

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Flexural Stress, brk, 1.3 mm/min, 50 mm span	90 – 100	MPa	ASTM D 790
Flexural Modulus, 2 mm/min	3200 – 3500	MPa	ISO 178
IMPACT			
Izod Impact, notched, 23°C	60	J/m	ASTM D 256
THERMAL			
HDT, 0.45 MPa, 3.2 mm, unannealed	134	°C	ASTM D 648
HDT, 1.82 MPa, 3.2mm, unannealed	122	°C	ASTM D 648
PHYSICAL			
Mold Shrinkage, flow, 24 hrs	0.7	%	ASTM D 955
Mold Shrinkage, xflow, 24 hrs	0.65	%	ASTM D 955
Density	1.66	g/cm ³	ISO 1183
Melt Volume Rate, MVR at 300°C/5.0 kg	11	cm ³ /10 min	ISO 1133
ELECTRICAL			
Dielectric Constant (Dk), 1.1 GHz	4.4 – 4.6	-	ASTM ES 7-83
Dissipation Factor (Df), 1.1 GHz	0.002 – 0.004	-	ASTM ES 7-83
INJECTION MOLDING			
Drying Temperature	105	°C	
Drying Time	3 – 5	hrs	
Melt Temperature	295 – 305	°C	
Nozzle Temperature	290 – 295	°C	
Front - Zone 3 Temperature	300 – 305	°C	
Middle - Zone 2 Temperature	290 – 295	°C	
Rear - Zone 1 Temperature	280 – 285	°C	
Mold Temperature	90	°C	
Back Pressure	9	MPa	
Screw Speed	100	rpm	

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